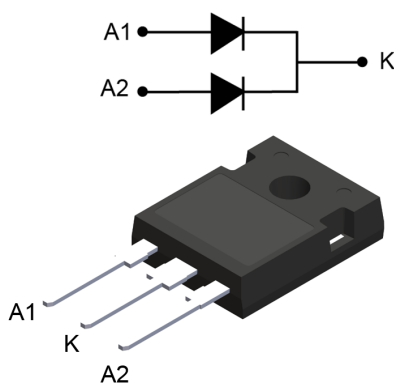



20 A 1200 V power Schottky silicon carbide diode



TO-247

Features

- AEC-Q101 qualified 
- No or negligible reverse recovery
- Switching behavior independent of temperature
- Robust high-voltage periphery
- PPAP capable
- Operating T_j from $-40\text{ }^\circ\text{C}$ to $175\text{ }^\circ\text{C}$
- ECOPACK[®] 2 compliant

Applications

- OBC (On Board Battery chargers)
- PHEV - EV charging stations
- Resonant LLC topology
- PFC functions (Power Factor Corrector)

Description

The SiC diode, available in TO-247, is an ultrahigh performance power Schottky rectifier. It is manufactured using a silicon carbide substrate. The wide band-gap material allows the design of a low V_F Schottky diode structure with a 1200 V rating.

Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC and secondary side applications, this ST SiC diode will boost the performance in hard switching conditions. This rectifier will enhance the performance of the targeted application. Its high forward surge capability ensures a good robustness during transient phases.

Product status link

[STPSC20H12CWY](#)

Product summary

$I_{F(AV)}$	2 x 10 A
V_{RRM}	1200 V
T_j (max.)	175 °C
V_F (typ.)	1.35 V

Product label



1 Characteristics

Table 1. Absolute ratings (limiting values per diode at 25 °C , unless otherwise specified)

Symbol	Parameter		Value	Unit	
V_{RRM}	Repetitive peak reverse voltage ($T_j = -40\text{ °C}$ to $+175\text{ °C}$)		1200	V	
$I_{F(RMS)}$	Forward rms current		25	A	
$I_{F(AV)}$	Average forward current	$T_c = 150\text{ °C}$, DC current	Per diode	10	A
			Per device	20	
I_{FRM}	Repetitive peak forward current		$T_c = 150\text{ °C}$, $T_j = 175\text{ °C}$, $\delta = 0.1$	42	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	$T_c = 25\text{ °C}$	71	A
		$t_p = 10\text{ ms}$ sinusoidal	$T_c = 150\text{ °C}$	60	
		$t_p = 10\text{ }\mu\text{s}$ square	$T_c = 25\text{ °C}$	420	
T_{stg}	Storage temperature range		-55 to +175	°C	
T_j	Operating junction temperature ⁽¹⁾		-40 to +175	°C	

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter		Value		Unit
			Typ.	Max.	
$R_{th(j-c)}$	Junction to case	Per diode	0.70	0.95	°C/W
		Per device	0.35	0.48	

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R ⁽¹⁾	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	5	60	μA
		$T_j = 150\text{ °C}$		-	30	400	
V_F ⁽²⁾	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 10\text{ A}$	-	1.35	1.50	V
		$T_j = 150\text{ °C}$		-	1.75	2.25	

1. Pulse test: $t_p = 10\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 500\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.03 \times I_{F(AV)} + 0.122 \times I_F^2_{(RMS)}$$

Table 4. Dynamic electrical characteristics (per diode)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$Q_{Cj}^{(1)}$	Total capacitive charge	$V_R = 800 \text{ V}$	-	57	-	nC
C_j	Total capacitance	$V_R = 0 \text{ V}, T_c = 25 \text{ }^\circ\text{C}, F = 1 \text{ MHz}$	-	725	-	pF
		$V_R = 800 \text{ V}, T_c = 25 \text{ }^\circ\text{C}, F = 1 \text{ MHz}$	-	47	-	

1. Most accurate value for the capacitive charge: $Q_{Cj}(V_R) = \int_0^{V_R} C_j(V) dV$

1.1 Characteristics (curves)

Figure 1. Forward voltage drop versus forward current (typical values, per diode)

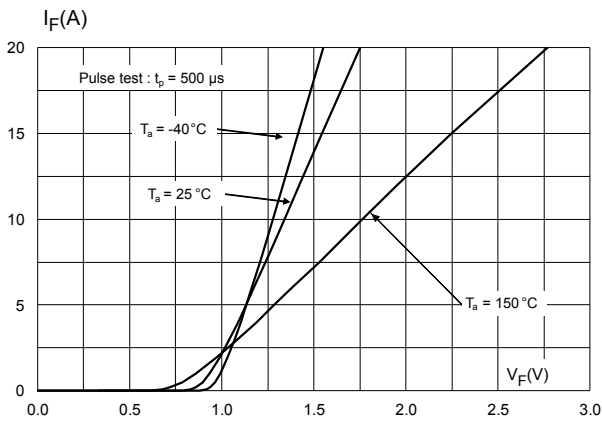


Figure 2. Reverse leakage current versus reverse voltage applied (typical values, per diode)

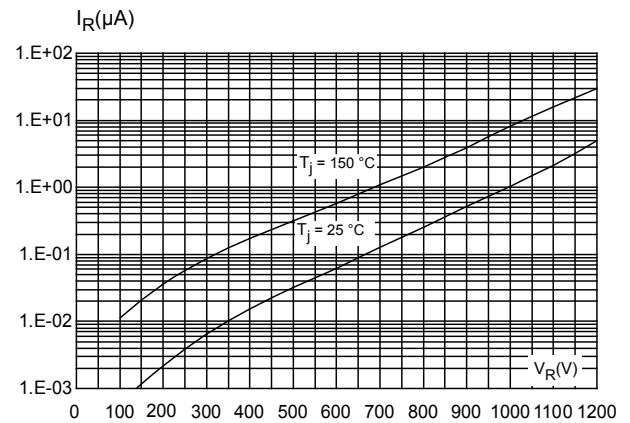


Figure 3. Peak forward current versus case temperature (per diode)

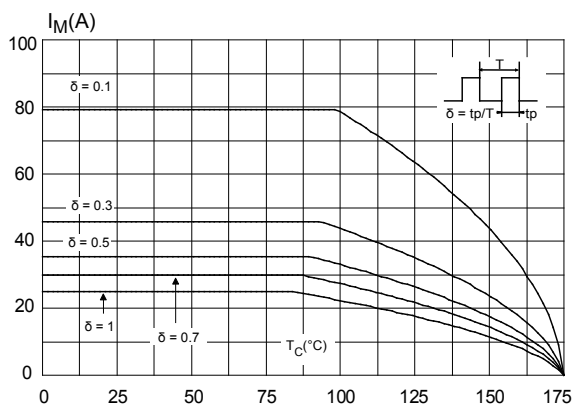


Figure 4. Junction capacitance versus reverse voltage applied (typical values, per diode)

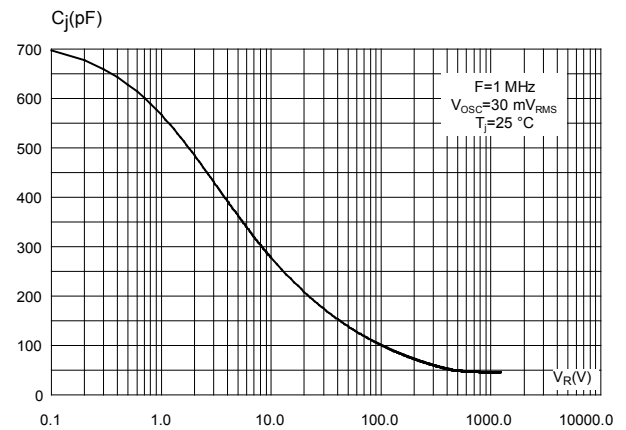
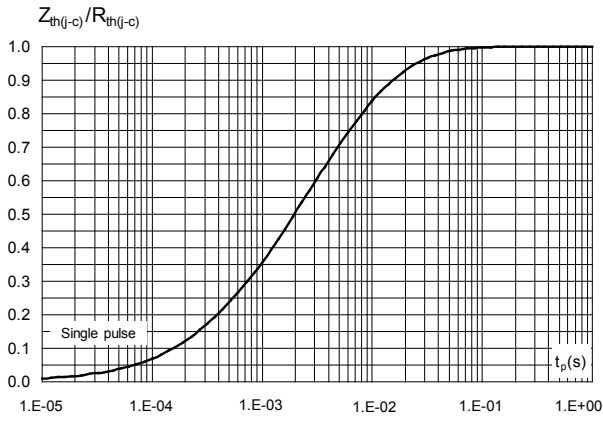
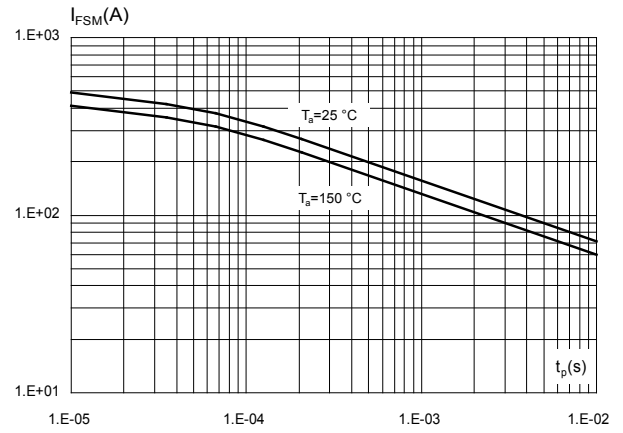
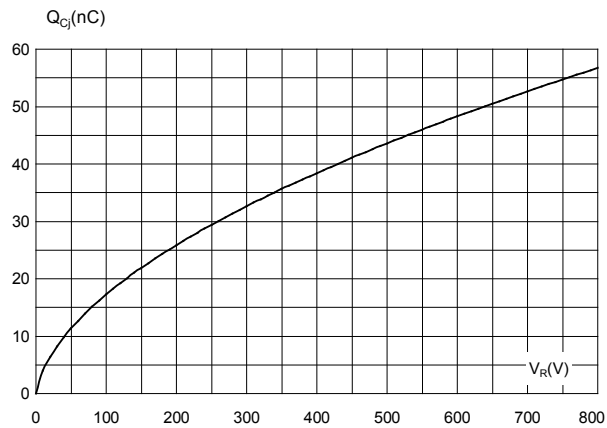


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

Figure 6. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform, per diode)

Figure 7. Total capacitive charges versus reverse voltage applied (typical values, per diode)


2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 TO-247 package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

Figure 8. TO-247 package outline

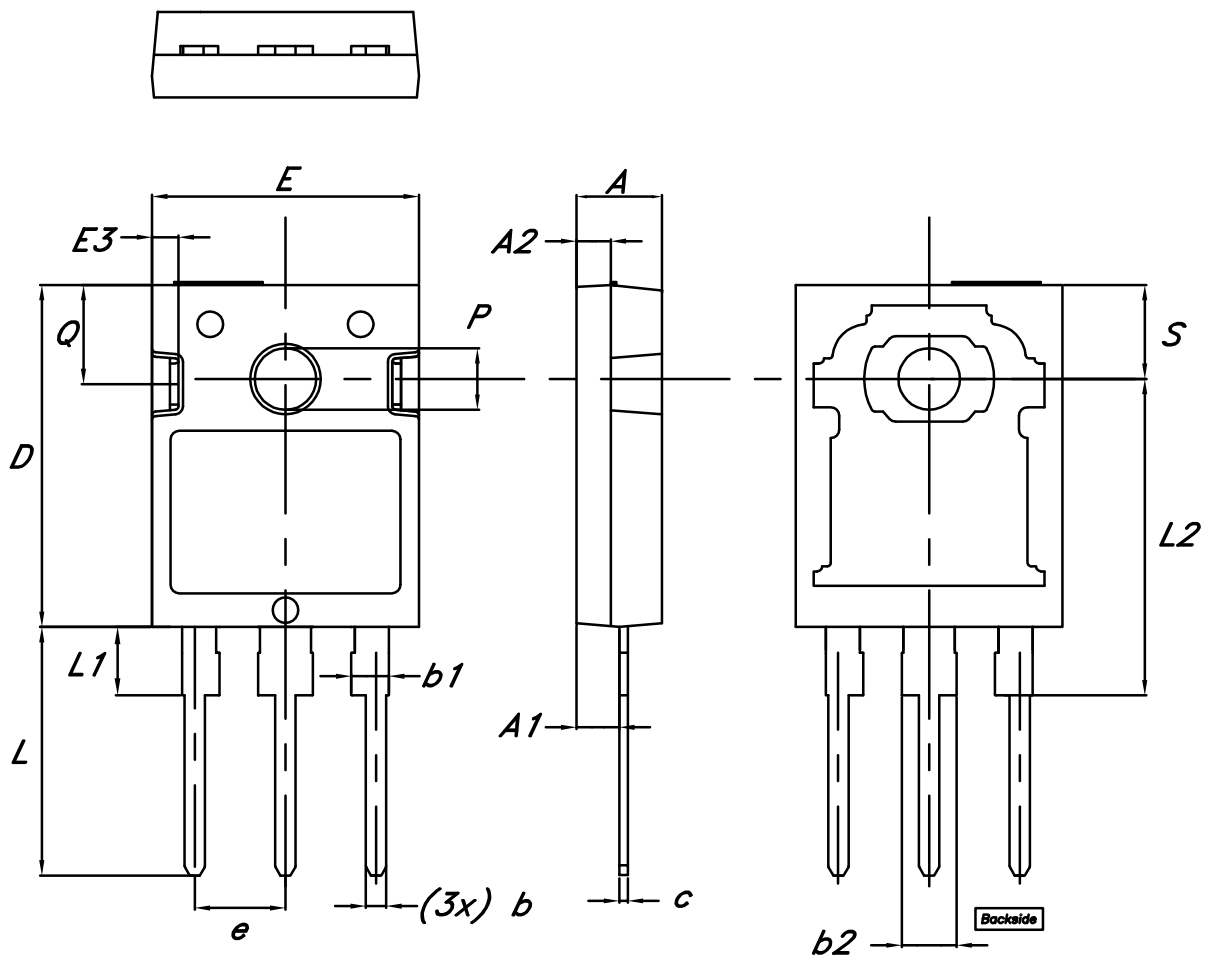


Table 5. TO-247 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
A1	2.20		2.60	0.086		0.102
A2	1.90	2.00	2.10	0.075	0.078	0.083
b	1.00		1.40	0.039		0.055
b1	2.00		2.40	0.078		0.094
b2	3.00		3.40	0.118		0.133
c	0.40		0.80	0.015		0.031
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
E3	1.45		1.65	0.057		0.065
e	5.30	5.45	5.60	0.209	0.215	0.220
L	14.20		14.80	0.559		0.582
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
ØP	3.55		3.65	0.139		0.143
Q	5.65		5.95	0.222		0.234
S	5.30	5.50	5.70	0.209	0.216	0.224

3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPSC20H12CWY	STPSC20H12CWY	TO-247	5.38 g	30	Tube

Revision history

Table 7. Document revision history

Date	Revision	Changes
12-Nov-2018	1	First issue.

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